



## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
L-1387QMP/1EGW	High Efficiency Red (GaAsP/GaP)	White Diffused	10	20	60°
			*6	*16	
	Green (GaP)		10	20	
			*10	*20	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous Flux: +/-15%.
- \*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red Green	627 565		nm	IF=20mA
λD [1]	Dominant Wavelength	High Efficiency Red Green	617 568		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red Green	45 30		nm	IF=20mA
C	Capacitance	High Efficiency Red Green	15 15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red Green	2 2.2	2.5 2.5	V	IF=20mA

Notes:

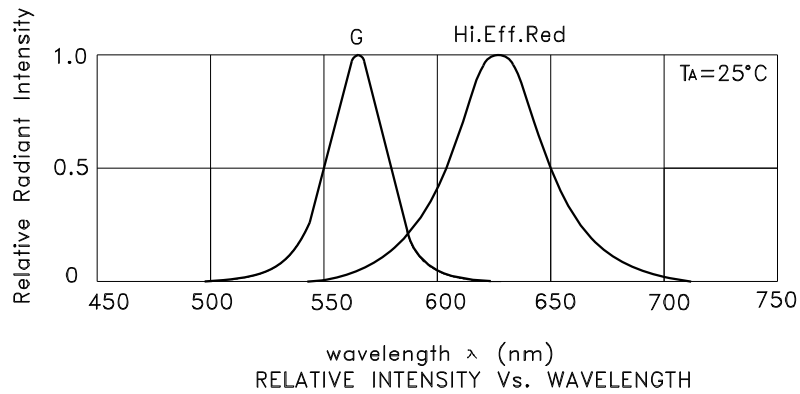
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.
3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

## Absolute Maximum Ratings at TA=25°C

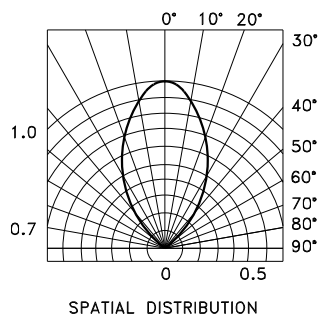
Parameter	High Efficiency Red	Green	Units
Power dissipation	75	62.5	mW
DC Forward Current	30	25	mA
Peak Forward Current [1]	160	140	mA
Operating / Storage Temperature	-40°C To +85°C		

Note:

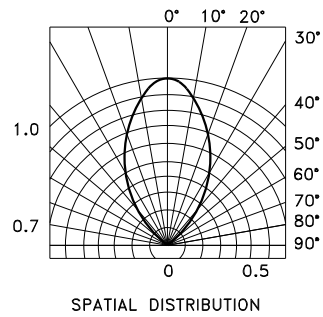
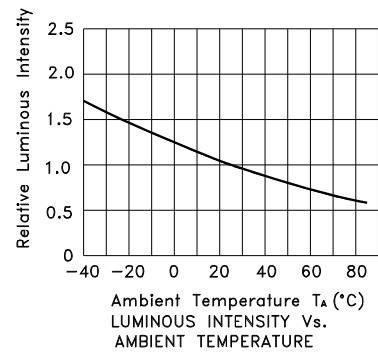
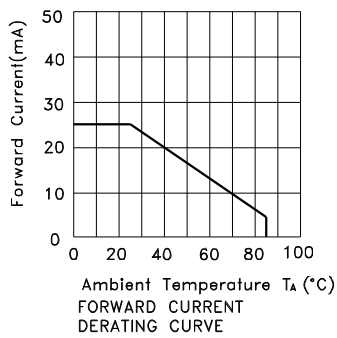
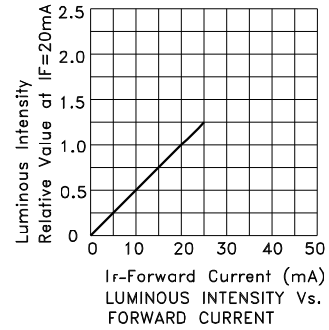
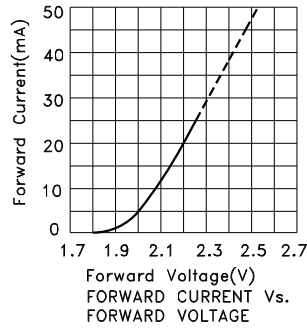
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



## L-1387QMP/1EGW High Efficiency Red

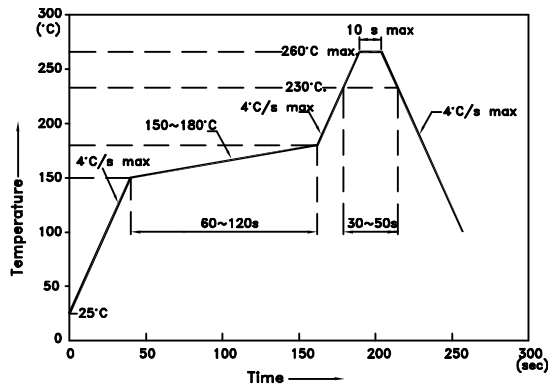


## Green



## L-1387QMP/1EGW

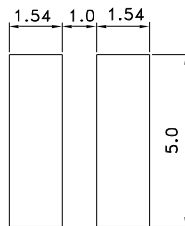
### Reflow Soldering Profile For Lead-free SMT Process.



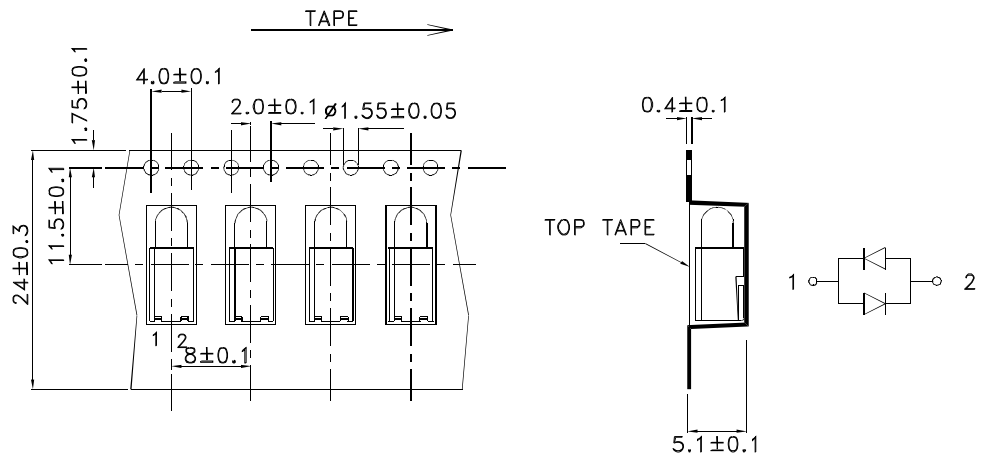
#### NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. No more than once.

### Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)

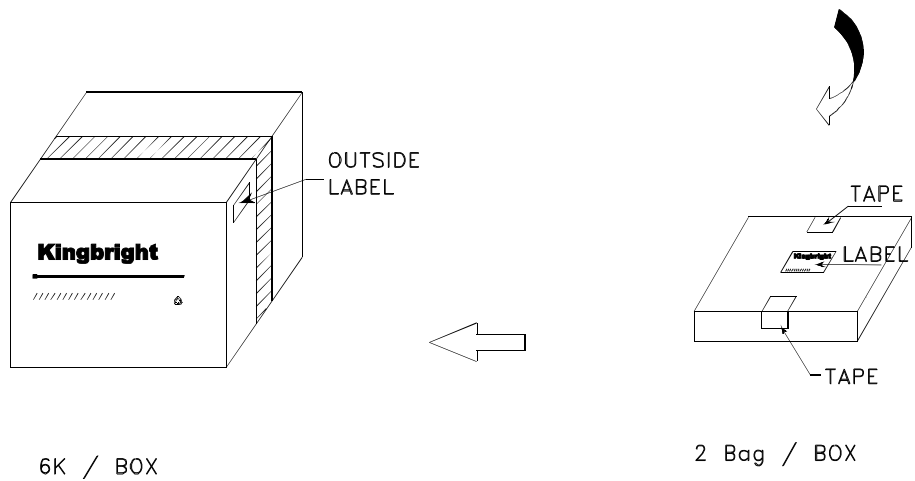
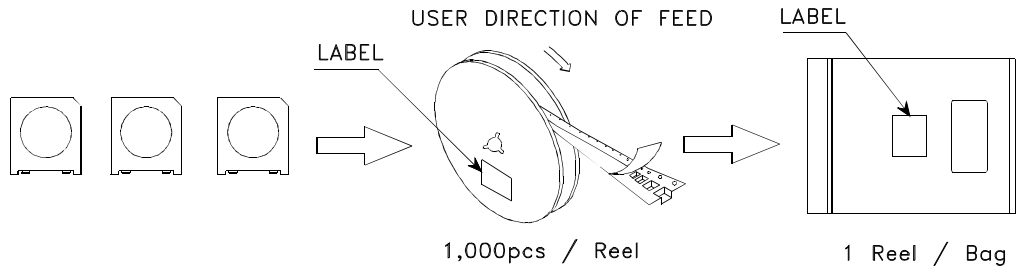



### Tape Dimensions (Units : mm)



**PACKING & LABEL SPECIFICATIONS**

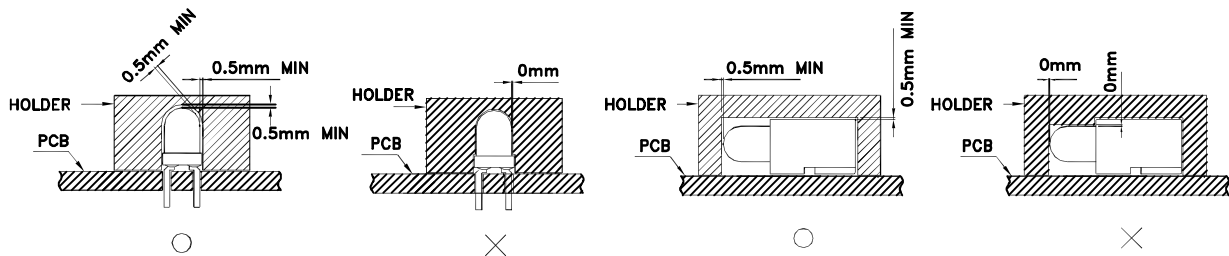
**L-1387QMP/1EGW**



<b>Kingbright</b>	
P/NO: L-1387QMPxxx	
QTY: 1000 pcs	Q.C. <span style="border: 1px solid black; border-radius: 50%; padding: 2px;">Q C XX XX XX PASSED</span>
S/N: XXXX	
CODE: XXX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	

## PRECAUTIONS

1. A moisture barrier bag (MBB) containing LEDs shall be kept in an environment with temperature below 40°C and humidity below 90% RH. A MBB shall be kept sealed until the LEDs contained in that bag are to be used immediately. Storage in an environment with temperature 5~30°C and humidity below 60% RH.
2. After a MBB has been opened, all LEDs contained in that bag shall complete soldering process within according to the conditions listed on the Kingbright MBB.
3. If the 10% spot of a humidity indicator card (HIC) indicates wet, LEDs shall be baked according to the conditions listed on the Kingbright MBB.
4. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



5. The tip of the soldering iron should never touch the lens epoxy.
6. After soldering, allow at least three minutes for the component to cool to room temperature before further operations.
7. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.

Detailed application notes are listed on our website.  
[http://www.kingbright.com/application\\_notes](http://www.kingbright.com/application_notes)